



1374.20289RC6

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. MAEJIMA, et al.

Serial No: 09/704,529

Filed: November 3, 2000

Title: WAFER HAVING CHAMFERED BEND PORTIONS IN THE  
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER  
AND THE CUT-AWAY PORTION OF THE WAFER

Group: 2814

Examiner: L. PHAM

**AMENDMENT AFTER FINAL REJECTION**

Box: AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 29, 2007

Sir:

In response to the Office Action dated December 5, 2006, please  
amend the above-identified application as listed below and as set forth on the  
following pages:

**Amendments to the Claims**

Remarks are included following the amendments